Unit: mm

TOSHIBA Field-Effect Transistor Silicon P-Channel MOS Type (U-MOSVI)

SSM3J327F

○ Power Management Switch Applications

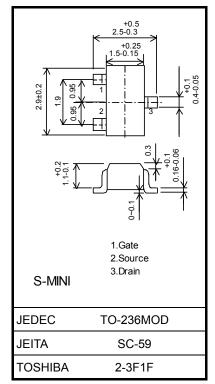
- 1.5-V drive
- Low ON-resistance: $R_{DS(ON)} = 242 \text{ m}\Omega \text{ (max)} (@V_{GS} = -1.5 \text{ V})$
 - $R_{DS(ON)} = 170 \text{ m}\Omega \text{ (max)} (@V_{GS} = -1.8 \text{ V})$
 - $R_{DS(ON)}$ = 125 m Ω (max) (@V_{GS} = -2.5 V)

 $R_{DS(ON)} = 95 \text{ m}\Omega \text{ (max)} (@V_{GS} = -4.5 \text{ V})$

Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol		Rating	Unit	
Drain-Source voltage		V _{DSS}		-20	V	
Gate-Source voltage		V _{GSS}		± 8	V	
Drain current	DC	I _D (Note 1)		-3.5	A	
	Pulse	I _{DP} (Note 1)		-7.0		
Power dissipation		P _D (Note 2)		600	mW	
			t = 1s	1200	11177	
Channel temperature		T _{ch}		150	°C	
Storage temperature range		T _{stg}		–55 to 150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.



Weight: 12 mg (typ.)

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

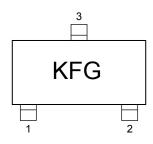
Note 1: The channel temperature should not exceed 150°C during use.

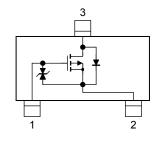
Note 2: Mounted on a FR4 board.

(25.4 mm \times 25.4 mm \times 1.6 mm, Cu Pad: 645 mm²)

Marking (Top View)

Equivalent Circuit





Electrical Characteristics (Ta = 25°C)

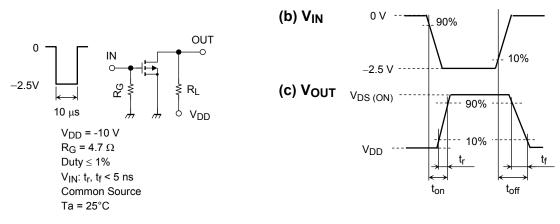
Chara	acteristic	Symbol	Test Conditions		Min	Тур.	Max	Unit
Drain Source breakdown veltage	V (BR) DSS	I _D = -1 mA, V _{GS} = 0 V		-20		—	V	
Drain-Source breakdown voltage		V (BR) DSX	I _D = -1 mA, V _{GS} = 5 V	(Note 4)	-15		_	V
Drain cut-off current		I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V		_		-1	μA
Gate leakage current		I _{GSS}	V_{GS} = ±8 V, V_{DS} = 0 V		_	—	±1	μA
Gate threshold voltage		V _{th}	V _{DS} = -3 V, I _D = -1 mA		-0.3		-1.0	V
Forward transfer a	admittance	Y _{fs}	V _{DS} = -3 V, I _D = -1.0 A	(Note 3)	2.8	5.6		S
Drain-source ON-resistance		I _D = -1.5 A, V _{GS} = -4.5 V	(Note 3)	_	80.5	95	mΩ	
	Pro (out)	I _D = -1.0 A, V _{GS} = -2.5 V	(Note 3)	_	99.5	125		
	R _{DS (ON)}	I _D = -0.5 A, V _{GS} = -1.8 V	(Note 3)	_	122	170		
		I _D = -0.25 A, V _{GS} = -1.5 V	(Note 3)	_	143	242		
Input capacitance		C _{iss}			_	290		
Output capacitance		C _{oss}	V _{DS} = -10 V, V _{GS} = 0 V f = 1 MHz		_	44		pF
Reverse transfer capacitance		C _{rss}			_	32		
Switching time	Turn-on time	t _{on}	V _{DD} = -10 V, I _D = -0.5 A		_	12.0		20
	Turn-off time	t _{off}	V_{GS} = 0 to -2.5 V, R_G = 4.7 Ω	2	_	46.2		ns
Total Gate Charge		Qg			_	4.6		
Gate-Source Charge		Q _{gs}	V _{DD} = -10 V, I _{DS} = -3.5 A, V _{GS} = -4.5V		_	3.4		nC
Gate-Drain Charge		Q _{gd}	VGS4.5V		— 1.2	_		
Drain-Source forward voltage		V _{DSF}	I _D = 3.5 A, V _{GS} = 0 V	(Note 3)	_	0.96	1.2	V

Note 3: Pulse test

Note 4: V_{DSX} mode (the application of a plus voltage between gate and source) may cause decrease in maximun rating of drain-source voltage

Switching Time Test Circuit

(a) Test Circuit



Notice on Usage

Let V_{th} be the voltage applied between gate and source that causes the drain current (I_D) to be low (-1 mA for the SSM3J327F). Then, for normal switching operation, V_{GS(on)} must be higher than V_{th}, and V_{GS(off)} must be lower than V_{th}. This relationship can be expressed as: V_{GS(off)} < V_{th} < V_{GS(on)}.

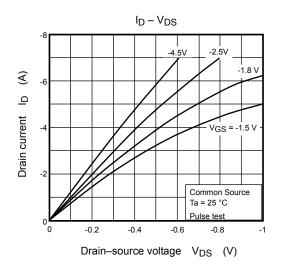
Take this into consideration when using the device.

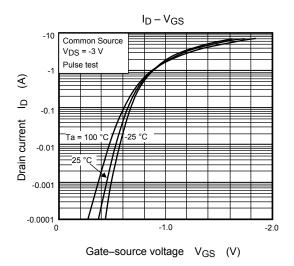
Handling Precaution

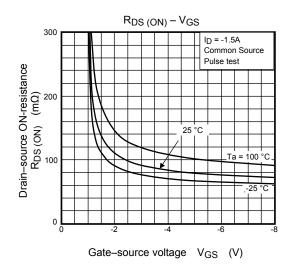
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

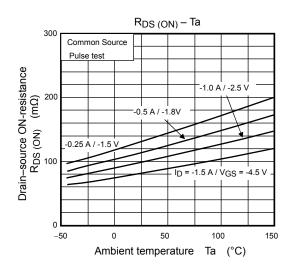
Thermal resistance $R_{th (ch-a)}$ and power dissipation P_D vary depending on board material, board area, board thickness and pad area. When using this device, please take heat dissipation into consideration

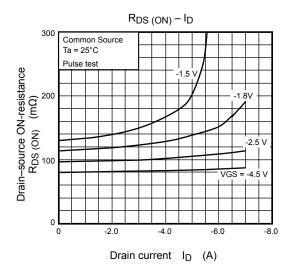
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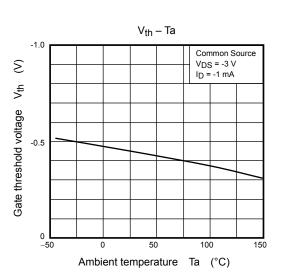




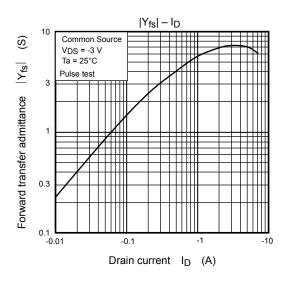


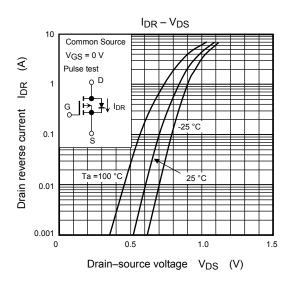


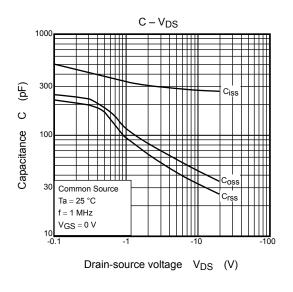


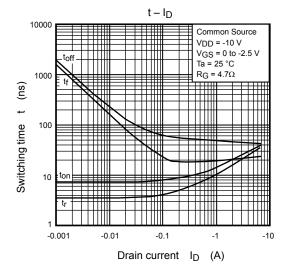


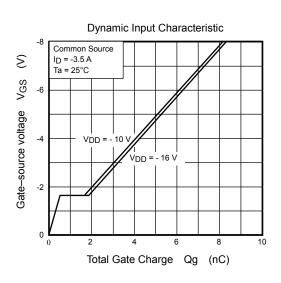
TOSHIBA



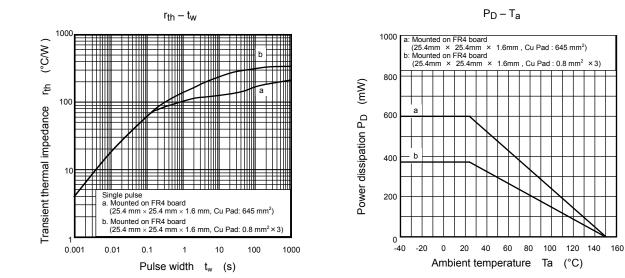








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